

## 1. General description

Hyperfast power diode in a 2-lead TO247 plastic package.

## 2. Features and benefits

- Fast switching and soft reverse recovery characteristics
- Low forward voltage drop
- Low leakage current
- Low reverse recovery current
- Reduces switching losses in associated MOSFET or IGBT
- Package meets UL94V0 which guaranteed by Epoxy Mold Compound

## 3. Applications

- UPS
- EV Charger
- Welding Machine
- Air Conditioner

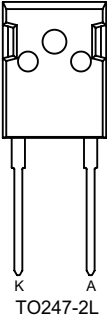
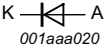
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V <sub>RRM</sub>	repetitive peak reverse voltage			650			V
I <sub>F(AV)</sub>	average forward current	δ = 0.5 ; square-wave pulse; T <sub>mb</sub> ≤ 91 °C; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		80			A
I <sub>FRM</sub>	repetitive peak forward current	δ = 0.5 ; t <sub>p</sub> = 25 μs; T <sub>mb</sub> ≤ 91 °C; square-wave pulse		160			A
I <sub>FSM</sub>	non-repetitive peak forward current	t <sub>p</sub> = 10 ms; T <sub>j(init)</sub> = 25 °C; sine-wave pulse; <a href="#">Fig. 4</a>		600			A
		t <sub>p</sub> = 8.3 ms; T <sub>j(init)</sub> = 25 °C; sine-wave pulse		660			A
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 80 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 6</a>		-	1.95	2.50	V
		I <sub>F</sub> = 80 A; T <sub>j</sub> = 150 °C; <a href="#">Fig. 6</a>		-	1.46	1.90	V
Dynamic characteristics							
t <sub>rr</sub>	reverse recovery time	I <sub>F</sub> = 1 A; V <sub>R</sub> = 30 V; dI <sub>F</sub> /dt = 50 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	44	-	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
mb	mb	mounting base; connected to cathod		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BYC80MW-650PT2	TO247-2L	BYC80MW-650PT2Q	Tube	30	TO247L-2L	10-Nov-2020

7. Marking

Table 4. Marking codes

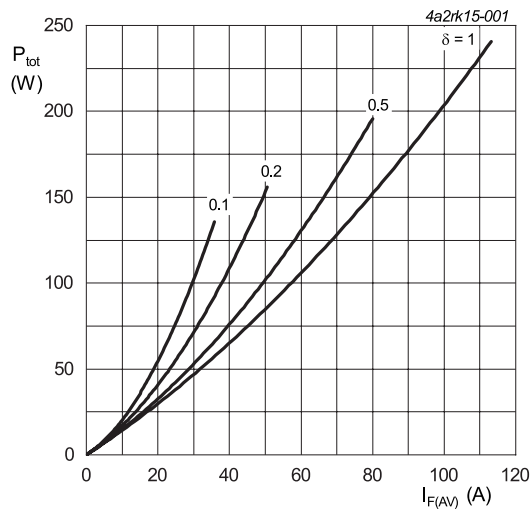
Type number	Marking codes
BYC80MW-650PT2	BYC80MW 650PT2

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

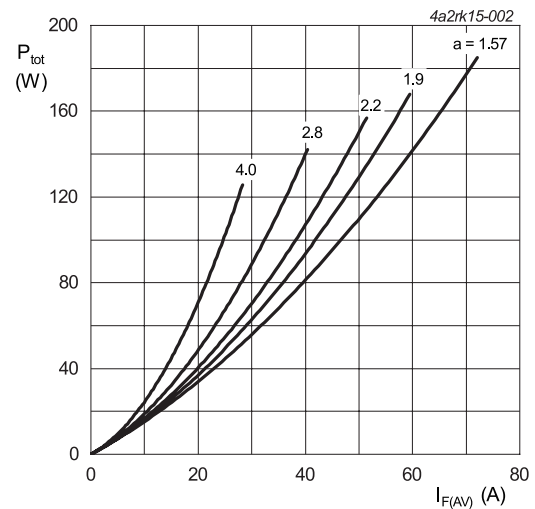
Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage			650	V
$V_{RWM}$	crest working reverse voltage			650	V
$V_R$	reverse voltage	DC		650	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 91\text{ }^{\circ}\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		80	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_{mb} \leq 91\text{ }^{\circ}\text{C}$ ; square-wave pulse		160	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$ ; sine-wave pulse; <a href="#">Fig. 4</a>		600	A
		$t_p = 8.3\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$ ; sine-wave pulse		660	A
$T_{stg}$	storage temperature			-65 to 175	$^{\circ}\text{C}$
$T_j$	junction temperature			-65 to 175	$^{\circ}\text{C}$



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$$V_o = 1.355\text{ V}; R_s = 0.0068\text{ }\Omega$$

**Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values**



$$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$$

$$V_o = 1.355\text{ V}; R_s = 0.0068\text{ }\Omega$$

**Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values**

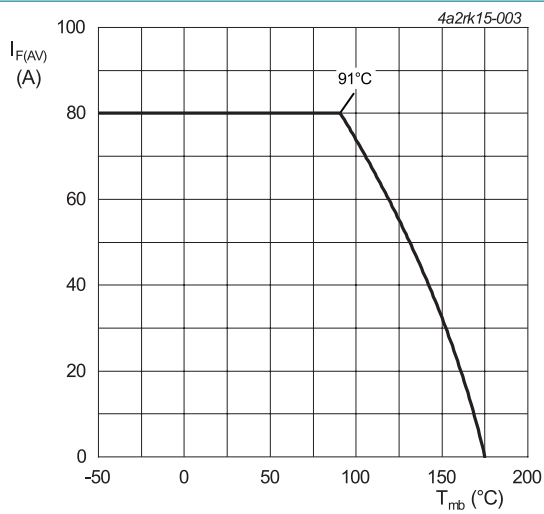


Fig. 3. Forward current as a function of mounting base temperature; maximum values

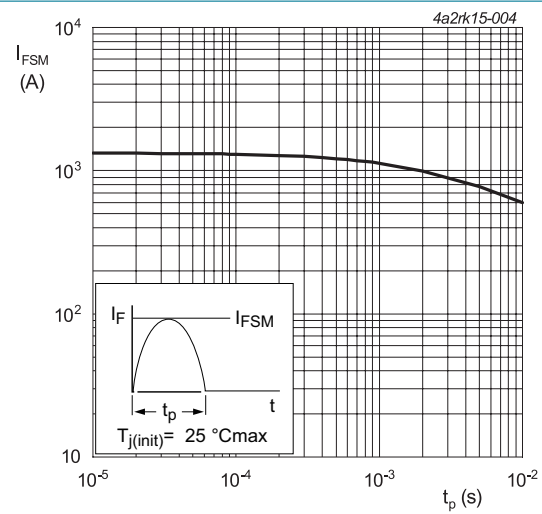


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<a href="#">Fig. 5</a>		-	-	0.43	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	40	-	K/W

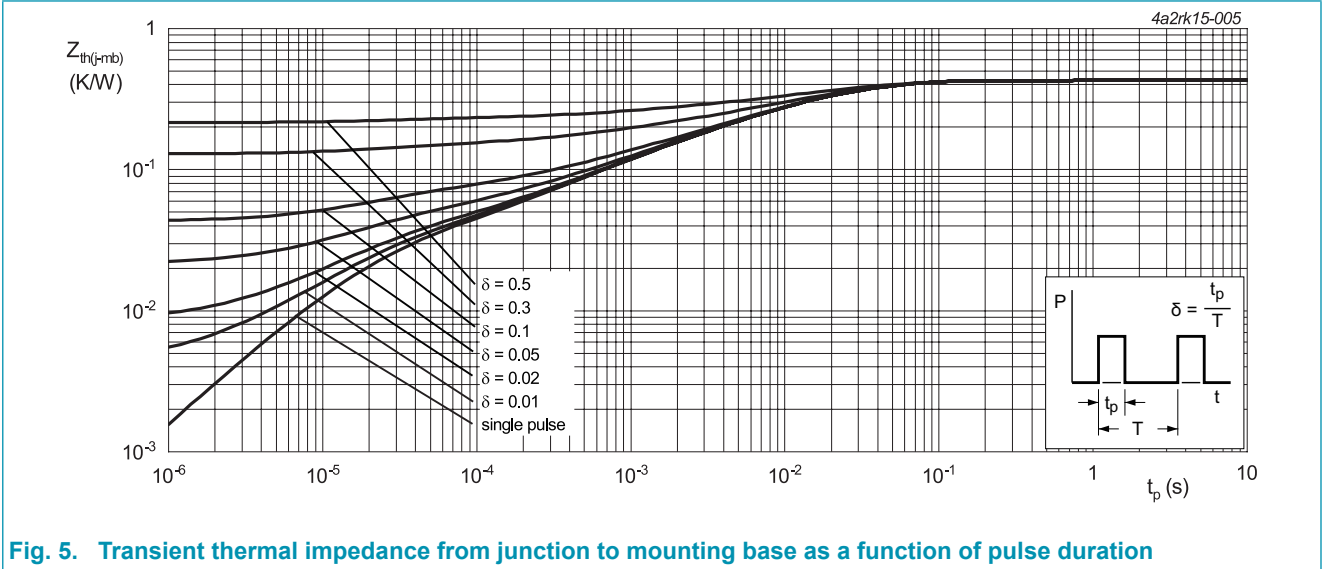
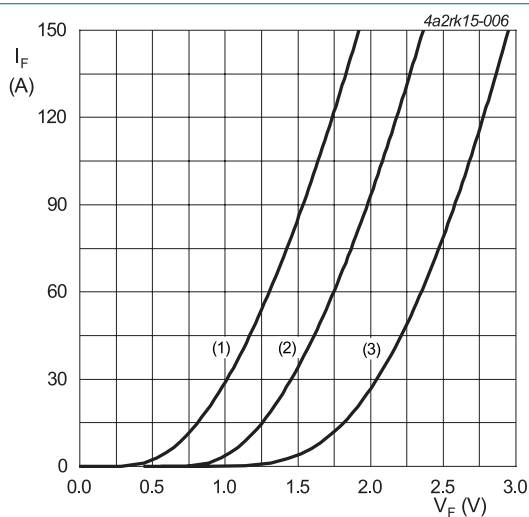


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 80 A; T <sub>J</sub> = 25 °C; <a href="#">Fig. 6</a>		-	1.95	2.50	V
		I <sub>F</sub> = 80 A; T <sub>J</sub> = 150 °C; <a href="#">Fig. 6</a>		-	1.46	1.90	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 650 V; T <sub>J</sub> = 25 °C		-	0.8	30	μA
		V <sub>R</sub> = 650 V; T <sub>J</sub> = 150 °C		-	0.5	5	mA
Dynamic characteristics							
Q <sub>r</sub>	reverse charge	I <sub>F</sub> = 50 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		-	320	-	nC
		I <sub>F</sub> = 50 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; T <sub>J</sub> = 125 °C; <a href="#">Fig. 7</a>		-	1500	-	nC
t <sub>rr</sub>	reverse recovery time	I <sub>F</sub> = 1 A; V <sub>R</sub> = 30 V; dI <sub>F</sub> /dt = 50 A/μs; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		-	44	-	ns
		I <sub>F</sub> = 50 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		-	60	-	ns
		I <sub>F</sub> = 50 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; T <sub>J</sub> = 125 °C; <a href="#">Fig. 7</a>		-	120	-	ns
I <sub>RM</sub>	peak reverse recovery current	I <sub>F</sub> = 50 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		-	11	-	A
		I <sub>F</sub> = 50 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; T <sub>J</sub> = 125 °C; <a href="#">Fig. 7</a>		-	25	-	A
E <sub>as</sub>	non-repetitive avalanche energy	T <sub>J(init)</sub> = 25 °C		67.5	-	-	mJ



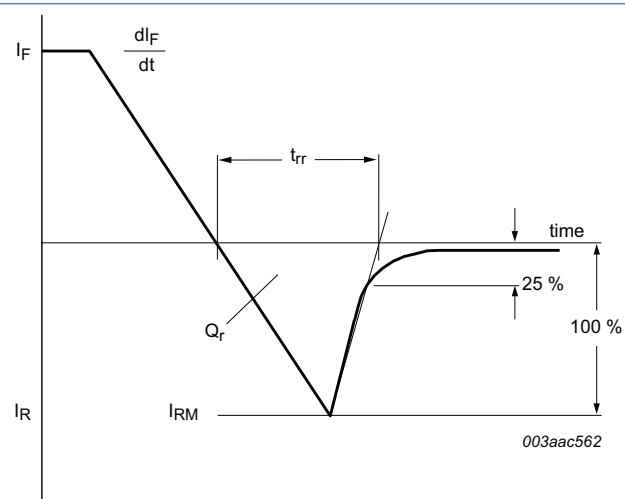
$V_o = 1.355 \text{ V}$ ;  $R_s = 0.0068 \text{ } \Omega$

(1)  $T_J = 150 \text{ }^\circ\text{C}$ ; typical values

(2)  $T_J = 150 \text{ }^\circ\text{C}$ ; maximum values

(3)  $T_J = 25 \text{ }^\circ\text{C}$ ; maximum values

**Fig. 6. Forward current as a function of forward voltage**



**Fig. 7. Reverse recovery definitions; ramp recovery**

11. Package outline

Plastic single-ended through-hole package; heatsink mounted;1 mounting hole; 2 leads TO-247

TO247-2L

The technical drawing illustrates the package outline of the BYC80MW-650PT2 diode. It includes three views: a top view showing the mounting hole (E) and leads (L, L1); a side view showing the package height (A) and lead length (Q, c); and a front view showing the mounting hole (P2) and lead length (D1, D2). Dimensions are labeled with letters and numbers, and specific values are provided in the table below.

UNIT	A	A <sub>1</sub>	b	b <sub>1</sub>	c	D	D <sub>1</sub> Ⓜ	D <sub>2</sub>	E	E <sub>1</sub>	E <sub>2</sub>	E <sub>3</sub>	e	L	L <sub>1</sub>	P <sub>2</sub>	p	Q	q	Ø
mm	5.20	2.10	1.40	2.20	0.70	20.60	16.20	1.20	15.75	14.22	5.20	1.80	10.90	20.72	4.75	3.60	3.70	2.60	6.18	7.30
	4.70	1.90	1.00	1.80	0.50	20.30	16.87	0.80	15.45	13.82	4.80	1.40	BSC	20.22	4.25	3.40	3.50	2.20	5.78	7.10

Note:

- Mold resin protrusion max 0.127mm.
- Metal exposed with Sn plating.

## 12. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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